SDLS035A - DECEMBER 1983 - REVISED APRIL 2003

- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

description

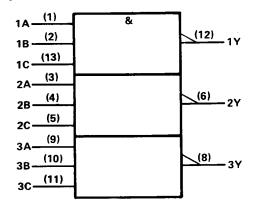
These devices contain three independent 3-input NAND gates.

The SN5410, SN54LS10, and SN54S10 are characterized for operation over the full military temperature range of $-55\,^{\circ}\text{C}$ to $125\,^{\circ}\text{C}$. The SN7410, SN74LS10, and SN74S10 are characterized for operation from $0\,^{\circ}\text{C}$ to $70\,^{\circ}\text{C}$.

FUNCTION TABLE (each gate)

11	NPUT	s	OUTPUT
A	В	С	Y
н	Н	н	L
L	X	×	н
Х	L	×	Н
Х	Х	L	Н

logic symbol†



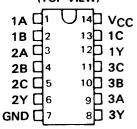
[†]This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, and N packages.

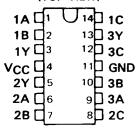
positive logic

$$Y = \overline{A \cdot B \cdot C}$$
 or $Y = \overline{A} + \overline{B} + \overline{C}$

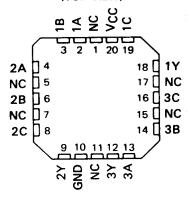
SN5410 . . . J PACKAGE SN54LS10, SN54S10 . . . J OR W PACKAGE SN7410 . . . N PACKAGE SN74LS10, SN74S10 . . . D OR N PACKAGE (TOP VIEW)



SN5410 . . . W PACKAGE (TOP VIEW)

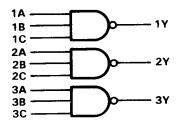


SN54LS10, SN54S10 . . . FK PACKAGE (TOP VIEW)

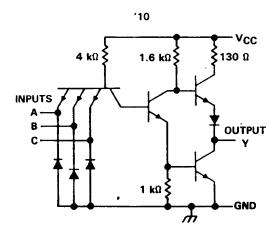


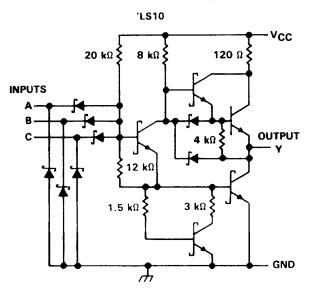
NC - No internal connection

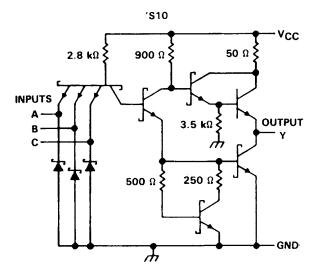
logic diagram (positive logic)



schematics (each gate)







Resistor values shown are nominal.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)	7 V
Input voltage: '10, 'S10	5.5 V
'LS10	7 V
Operating free-air temperature range: SN54'	-55°C to 125°C
SN74'	0°C to 70°C
Storage temperature range	-65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.



recommended operating conditions

		SN5410			SN7410			
	MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
V _{CC} Supply voltage	4.5	5	5.5	4.75	5	5.25	V	
V _{IH} High-level input voltage	2			2			V	
VIL Low-level input voltage			0.8			0.8	V	
IOH High-level output current			- 0.4			- 0.4	mA	
IOL Low-level output current			16			16	mA	
TA Operating free-air temperature	- 55		125	0		70	°C	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS T			SN541)		SN741	0		
		MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT		
VIK	V _{CC} = MIN,	I _I = - 12 mA				- 1.5			- 1.5	V
VOH	V _{CC} = MIN,	V _{1L} = 0.8 V,	I _{OH} = - 0.4 mA	2.4	3.4		2.4	3.4		V
VOL	V _{CC} = MIN,	V _{IH} = 2 V,	I _{OL} = 16 mA		0.2	0.4		0.2	0.4	V
11	V _{CC} = MAX,	V ₁ = 5.5 V				1			1	mA
ΉΗ	V _{CC} = MAX,	V ₁ = 2.4 V				40			40	μА
IL	V _{CC} = MAX,	V ₁ = 0.4 V			-	- 1.6			- 1.6	mA
¹os§	V _{CC} = MAX			- 20		- 55	- 18		- 55	mA
Iссн	V _{CC} = MAX,	V1 = 0 V			3	6		3	6	mA
¹ CCL	V _{CC} = MAX,	V ₁ = 4.5 V			9	16.5		9	16.5	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$ (see note 2)

242445750	FROM	то					
PARAMETER	(INPUT)	(OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
^t PLH	A, B or C				11	22	ns
^t PHL	A, B 01 C	Ť	$R_L = 400 \Omega$, $C_L = 15 p$	F	7	15	ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.



[‡] All typical values are at V_{CC} = 5 V, T_A = 25°C.

[§] Not more than one output should be shorted at a time.

SN54LS10, SN74LS10, TRIPLE 3-INPUT POSITIVE-NAND GATES

SDLS035 - DECEMBER 1983 - REVISED MARCH 1988

recommended operating conditions

		SN54LS10			SN74LS10		
	MIN	NOM	MAX	MIN	NOM	MAX	UNIT
V _{CC} Supply voltage	4.5	5	5.5	4.75	5	5.25	v
V _{IH} High-level input voltage	2			2			V
VIL Low-level input voltage			0.7			8.0	V
IOH High-level output current			- 0.4			- 0.4	mA
IOL Low-level output current			4			8	mA
T _A Operating free-air temperature	– 55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS †			SN54LS	10	İ	SN74LS	S10 ·	
FARAMETER				TYP‡	MAX	MIN	TYP‡	MAX	UNIT
VIK	V _{CC} = MIN, I _I = - 18	mA			- 1.5			- 1.5	٧
V _{ОН}	V _{CC} = MIN, V _{IL} = MA	AX, I _{OH} = -0.4 mA	2.5	3.4		2.7	3.4		٧
V	V _{CC} = MIN, V _{IH} = 2 \	V, I _{OL} = 4 mA		0.25	0.4			0.4	
VOL	V _{CC} = MIN, V _{IH} = 2 \	V, I _{OL} = 8 mA					0.25	0.5	\ \
l ₁	V _{CC} = MAX, V _I = 7 V				0.1			0.1	mA
ЧН	V _{CC} = MAX, V _I = 2.7 V	V			20			20	μΑ
IιΓ	V _{CC} = MAX, V ₁ = 0.4	V		-	- 0.4			- 0.4	mA
los§	V _{CC} = MAX		- 20		- 100	- 20		- 100	mA
Іссн	V _{CC} = MAX, V _I = 0 V			0.6	1.2		0.6	1.2	mΑ
ICCL	V _{CC} = MAX, V ₁ = 4.5 V	V		1.8	3.3		1.8	3.3	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$ (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
tPLH	A, B or C	Y	$R_1 = 2 k\Omega$, $C_1 = 15 pF$		9	15	ns
^t PHL		·			10	15	ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.



[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$. § Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.

recommended operating conditions

			SN54S10			SN74S10		
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.8			0.8	٧
ЮН	High-level output current			– 1			- 1	mA
loL	Low-level output current		·	20			20	mA
TA	Operating free-air temperature	- 55		125	0		70	°c

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEGT COMPLETIONS T			SN54S10			SN74S	10	UNIT	
FANAMETER		TEST CONDITIONS †				MAX	MIN	TYP‡	MAX	UNIT
v _{IK}	V _{CC} = MIN,	I _I = -18 mA				-1.2			-1.2	٧
V _{OH}	V _{CC} ≈ MIN,	V _{IL} = 0.8 V,	I _{OH} = - 1 mA	2.5	3.4		2.7	3.4		٧
V _{OL}	V _{CC} = MIN,	V _{IH} = 2 V,	I _{OL} = 20 mA			0.5			0.5	V
l _l	V _{CC} = MAX,	V _I = 5.5 V				1			1	mA
IIH	V _{CC} = MAX,	V _I = 2.7 V				50			50	μА
†IL	V _{CC} = MAX,	V _I = 0.5 V				-2			-2	mA
IOS§	V _{CC} = MAX			-40		-100	-40	·	-100	mA
Iссн	V _{CC} = MAX,	V _I = 0 V			7.5	12		7.5	12	mA
¹ CCL	V _{CC} = MAX,	V _I = 4.5 V	,		15	27		15	27	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$ (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONE	DITIONS	MIN	TYP	MAX	UNIT
^t PLH			R _L = 280 Ω,	C ₁ = 15 pF		3	4.5	ns
^t PHĿ	A D . O	V	NL - 200 12,	CL - 19 PF		3	5	ns
^t PLH	A, B or C	Y	D 200 O	C = 50 = 5		4.5		ns
^t PHL			R _L = 280 Ω,	CL = 50 pF		5		ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.



[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$. § Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.





28-Feb-2005

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	n MSL Peak Temp ⁽³⁾
JM38510/00103BCA	OBSOLETE	CDIP	J	14		None	Call TI	Call TI
JM38510/00103BDA	OBSOLETE	CFP	W	14		None	Call TI	Call TI
JM38510/07005BCA	ACTIVE	CDIP	J	14	1	None	Call TI	Level-NC-NC-NC
JM38510/07005BDA	ACTIVE	CFP	W	14	1	None	Call TI	Level-NC-NC-NC
JM38510/30005B2A	ACTIVE	LCCC	FK	20	1	None	Call TI	Level-NC-NC-NC
JM38510/30005BCA	ACTIVE	CDIP	J	14	1	None	Call TI	Level-NC-NC-NC
JM38510/30005BDA	ACTIVE	CFP	W	14	1	None	Call TI	Level-NC-NC-NC
JM38510/30005SCA	ACTIVE	CDIP	J	14	1	None	Call TI	Level-NC-NC-NC
JM38510/30005SDA	ACTIVE	CFP	W	14	1	None	Call TI	Level-NC-NC-NC
SN5410J	OBSOLETE	CDIP	J	14		None	Call TI	Call TI
SN54LS10J	ACTIVE	CDIP	J	14	1	None	Call TI	Level-NC-NC-NC
SN54S10J	ACTIVE	CDIP	J	14	1	None	Call TI	Level-NC-NC-NC
SN7410N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN7410N3	OBSOLETE	PDIP	N	14		None	Call TI	Call TI
SN74LS10D	ACTIVE	SOIC	D	14	50	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74LS10DR	ACTIVE	SOIC	D	14	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74LS10N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS10N3	OBSOLETE	PDIP	N	14		None	Call TI	Call TI
SN74LS10NSR	ACTIVE	SO	NS	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74S10D	ACTIVE	SOIC	D	14	50	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74S10N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74S10N3	OBSOLETE	PDIP	N	14		None	Call TI	Call TI
SN74S10NSR	ACTIVE	SO	NS	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SNJ5410J	OBSOLETE	CDIP	J	14		None	Call TI	Call TI
SNJ5410W	OBSOLETE	CFP	W	14		None	Call TI	Call TI
SNJ5410WA	OBSOLETE	CFP	WA	14		None	Call TI	Call TI
SNJ54LS10FK	ACTIVE	LCCC	FK	20	1	None	Call TI	Level-NC-NC-NC
SNJ54LS10J	ACTIVE	CDIP	J	14	1	None	Call TI	Level-NC-NC-NC
SNJ54LS10W	ACTIVE	CFP	W	14	1	None	Call TI	Level-NC-NC-NC
SNJ54S10FK	ACTIVE	LCCC	FK	20	1	None	Call TI	Level-NC-NC-NC
SNJ54S10J	ACTIVE	CDIP	J	14	1	None	Call TI	Level-NC-NC-NC
SNJ54S10W	ACTIVE	CFP	W	14	1	None	Call TI	Level-NC-NC-NC

(1) The marketing status values are defined as follows: **ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.



PACKAGE OPTION ADDENDUM

28-Feb-2005

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - May not be currently available - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

None: Not yet available Lead (Pb-Free).

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDECindustry standard classifications, and peak solder temperature.

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14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB



FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AB.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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